

**PATENT ASSIGNMENT**

Electronic Version v07  
 Stylesheet Version v02

SUBMISSION TYPE:		NEW ASSIGNMENT	<b>APPLICATION NUMBER</b> 10/708871		
NATURE OF CONVEYANCE:		ASSIGNMENT OF ASSIGNOR'S INTEREST			
CONVEYING PARTY DATA					
Name		Execution Date			
Tung-Liang Yang		2004-03-29			
Yi-Nan Chen		2004-03-29			
RECEIVING PARTY DATA					
Name	Street Address	Internal Address	City	State/Country	Postal Code
NANYA TECHNOLOGY CORP.	HWA-YA TECHNOLOGY PARK 669, FUHSING 3 RD.,	KUEISHAN	Tao-Yuan Hsien	TAIWAN	
CORRESPONDENCE DATA					
FAX NUMBER: 886229295950					
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>					
When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.					
CUSTOMER NUMBER: 027765					
NAME OF PERSON SIGNING:		WINSTON HSU			
DATE SIGNED:		2004-03-29			
Total Attachments: 2 source=NTCP0030ASS1.tif source=NTCP0030ASS2.tif					

CH \$40.00 500801 10708871

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNORS (Inventors):**

Name: Tung-Liang Yang Nationality: R.O.C.

Address: 9F, No. 18-3, Chang-Le 4 St., Chung-Li City, Tao-Yuan Hsien, Taiwan, R.O.C.

Name: Yi-Nan Chen Nationality: R.O.C.

Address: No. 4, Lane 151, Chien-Min Rd., Pei-Tou, Taipei City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **NANYA TECHNOLOGY CORP.**

(hereinafter 'Assignee'), of (Assignee address)

**HWA-YA TECHNOLOGY PARK 669, FUHSING 3 RD., KUEISHAN, Tao-Yuan Hsien, Taiwan, R.O.C.**

, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"METHOD OF IMPROVING ALIGNMENT FOR SEMICONDUCTOR FABRICATION"**

Which is found in :

- (a) \_\_\_\_\_ U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this \_\_\_\_\_ (Date of signing).

(Type name of inventor)

Signature of INVENTOR

Tung-Liang Yang

*Tung-Liang Yang*

Yi-Nan Chen

*Yi-Nan Chen*